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**PRESSURE SENSITIVE ADHESIVE SHEET FOR SEMICONDUCTOR
WAFER PROCESSING**

ABSTRACT

Disclosed herein is a pressure sensitive adhesive sheet
for fixing a semiconductor wafer in semiconductor wafer
processing in vacuum, comprising a substrate and,
5 superimposed on one side or both sides thereof, a layer of
ultraviolet curable pressure sensitive adhesive
composition comprising an ultraviolet curable copolymer
having ultraviolet polymerizable groups as side chains and
a phosphorous photopolymerization initiator. The
10 invention is intended to provide a pressure sensitive
adhesive sheet for semiconductor wafer processing which,
even in the processing of a semiconductor wafer in vacuum,
is free from generating gases from the pressure sensitive
adhesive sheet to thereby enable avoiding wafer deformation
15 attributed to evaporated gas components and adhesive
transfer caused thereby.



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